CLAIMS

1. A sealable resin sheet comprising:

a first sealable resin layer and a second sealable resin layer sequentially in a thickness direction, wherein

the first sealable resin layer contains a first thermosetting resin and a first inorganic filler, and has, after curing, an average coefficient of thermal expansion of 20 ppm/℃ or less in a temperature range from -40℃ to a glass transition temperature of the first sealable resin layer,

the second sealable resin layer contains a second thermosetting resin and a second inorganic filler, and has, after curing, an average coefficient of thermal expansion of 20 ppm/℃ or less in a temperature range from -40℃ to a glass transition temperature of the second sealable resin layer,

a content ratio of the first inorganic filler in the first sealable resin layer differs from a content ratio of the second inorganic filler in the second sealable resin layer, and

a ratio of a thickness of the first sealable resin layer to an entire thickness of the sealable resin sheet is 0.37 or more and 0.82 or less.

2. The sealable resin sheet according to claim 1, wherein the first sealable resin layer has a thickness of 90 μm or more.

3. The sealable resin sheet according to claim 1 or 2, wherein the first sealable resin layer has the lowest melt viscosity of 120 kPa·s or more.

4. The sealable resin sheet according to any one of claims 1 to 3, wherein the first sealable resin layer has the lowest melt viscosity of 260 kPa·s or less.

5. The sealable resin sheet according to any one of claims 1 to 4, further comprising:

a third sealable resin layer between the first sealable resin layer and the second sealable resin layer, wherein

the third sealable resin layer contains a third thermosetting resin and a third inorganic filler, and has, after curing, an average coefficient of thermal expansion of 20 ppm/℃ or less in a temperature range from -40℃ to a glass transition temperature of the third sealable resin layer.

6. The sealable resin sheet according to claim 5, wherein

the third sealable resin layer is in direct contact with the first sealable resin layer, and

a ratio of a total thickness of a thickness of the first sealable resin layer and a thickness of the third sealable resin layer to an entire thickness of the sealable resin sheet is 0.4 or more and 0.82 or less.

7. The sealable resin sheet according to any one of claims 1 to 6, wherein

the content ratio of the inorganic filler in each of the sealable resin layers is 75% by mass or more.

8. The sealable resin sheet according to any one of claims 1 to 7, wherein

the content ratio of the inorganic filler in each of the sealable resin layers is 90% by mass or less.

9. An electronic component device comprising:

a base material;

an electronic component chip mounted on the base material in a state in which the electronic component chip faces the base material through a gap; and

a cured resin portion formed of the sealable resin sheet according to any one of claims 1 to 8, the cured resin portion encapsulating the electronic component chip and the gap.